



## Customer Information Notification

2020030271

**Issue Date:** 25-Mar-2020

**Effective Date:** 26-Mar-2020

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

**This notice is NXP Company Proprietary.**



# QUALITY

### Change Category

- |  |  |  |   |   |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process   | <input type="checkbox"/> Assembly Process  | <input type="checkbox"/> Product Marking           | <input type="checkbox"/> Test Location  | <input type="checkbox"/> Design                         |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials  | <input type="checkbox"/> Mechanical Specification  | <input type="checkbox"/> Test Process   | <input type="checkbox"/> Errata                         |
| <input type="checkbox"/> Wafer Fab Location  | <input type="checkbox"/> Assembly Location   | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware            | <input checked="" type="checkbox"/> Other - Data Sheet Update - Corrections / Clarifications |  |   |   |

**MC33GD3100 Data Sheet  
Update to Rev 9.0  
(Corrections and Technical  
Clarifications)**

### Description

NXP Semiconductors announces the data sheet update to revision 9.0 for the GD3100 devices associated with this notification.

The revision history included in the updated document provides a detailed description of the changes. Changes are summarized below.

MC33GD3100 rev 9.0 Data Sheet Updates:

1. Figure 1: Updated simplified application circuit diagram
2. Table 2: Updated NC2 and NC13 pin definitions
3. Section 6.3.1.10: Updated NC13 pin notes to cover GD3160 forward-compatibility
4. Table 4: Updated for typos and to use uniform current polarity definition
5. Section 8.3: Updated description to reflect existing 15A max current specification
6. Figure 18: Updated active clamp application circuit
7. Figure 23: Updated desaturation pin application circuit to include a protection diode
8. Table 7: Updated to correct typo on clearance distance parameter value

## 9. Removed former Section 9.4.5: "VCE desaturation management via the ISENSE pin"

**\*\* Documentation change only for customer clarifications - absolutely no changes to the device / product \*\***

The new MC33GD3100 rev 9.0 data sheet may be obtained from the secure DocStore portal:  
<https://www.docstore.nxp.com/products?path=/content/docstore/product-hierarchy/Power-train-and-electrification/HV-Gate-Driver/Datasheet&folderuid=098c098e-94d0-4eae-b212-dfc3fa5e0efa#paging:currentPage=0|paging:number=12>

Corresponding ZVEI Delta Qualification Matrix ID: SEM-DS-02

### **Reason**

The data sheet has been updated to provide additional detail on recommended application circuits, describe forward compatibility to GD3160 in development, and remedy typos for improved readability.

### **Identification of Affected Products**

Product identification does not change

## **Anticipated Impact on Form, Fit, Function, Reliability or Quality**

No impact on form, fit, function, reliability or quality.

### **Data Sheet Revision**

A new datasheet will be issued

## **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** Travis Alexander  
**Position** System and Applications Engineer  
**e-mail address** [travis.alexander@nxp.com](mailto:travis.alexander@nxp.com)

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

## **About NXP Semiconductors**

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

[NXP](#) | [Privacy Policy](#) | [Terms of Use](#)

NXP Semiconductors  
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.

Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
MC33GD3100A3EK	935381426574	MC33GD3100A3EK	HV Isolated Gate Driver	SOT1762-1	SSOP32	RFS	Driver & Energy Systems
MC33GD3100EK	935312748574	MC33GD3100EK	HV Isolated Gate Driver	SOT1762-1	SSOP32	RFS	Driver & Energy Systems